

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0737827100](#)  
**Status:** **Active**  
**Overview:** [hdm](#)  
**Description:** 2.00mm (.079") Pitch HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits

**Documents:**

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

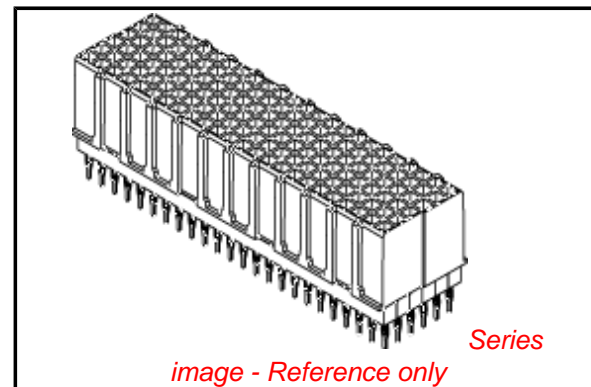
CSA LR19980  
 UL E29179

**General**

Product Family Backplane Connectors  
 Series [73782](#)  
 Application Backplane, Mezzanine  
 Component Type PCB Header  
 Overview [hdm](#)  
 Product Name HDM®  
 Style N/A

**Physical**

Circuits (Loaded) 144  
 Circuits (maximum) 144  
 Color - Resin Black  
 Durability (mating cycles max) 200  
 First Mate / Last Break No  
 Flammability 94V-0  
 Guide to Mating Part No  
 Keying to Mating Part None  
 Material - Metal Phosphor Bronze  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin-Lead  
 Material - Resin High Temperature Thermoplastic  
 Number of Columns 24  
 Number of Pairs Open Pin Field  
 Number of Rows 6  
 Orientation Vertical  
 PC Tail Length (in) 0.138 In  
 PC Tail Length (mm) 3.50 mm  
 PCB Retention None  
 PCB Thickness Recommended (in) 0.055 In  
 PCB Thickness Recommended (mm) 1.40 mm  
 Packaging Type Tube  
 Pitch - Mating Interface (in) 0.079 In  
 Pitch - Mating Interface (mm) 2.00 mm  
 Plating min: Mating (µin) 30  
 Plating min: Mating (µm) 0.75  
 Plating min: Termination (µin) 100  
 Plating min: Termination (µm) 2.5  
 Polarized to PCB No  
 Stackable Yes  
 Surface Mount Compatible (SMC) Yes  
 Temperature Range - Operating -55°C to +105°C



**EU RoHS**

**ELV and RoHS  
 Compliant**  
**REACH SVHC  
 Contains SVHC: No**  
**Halogen-Free  
 Status  
 Not Reviewed**

**China RoHS**



**Need more information on product  
 environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73782Series](#)

**Mates With**

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Termination Interface: Style Through Hole

### **Electrical**

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

### **Solder Process Data**

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

### **Material Info**

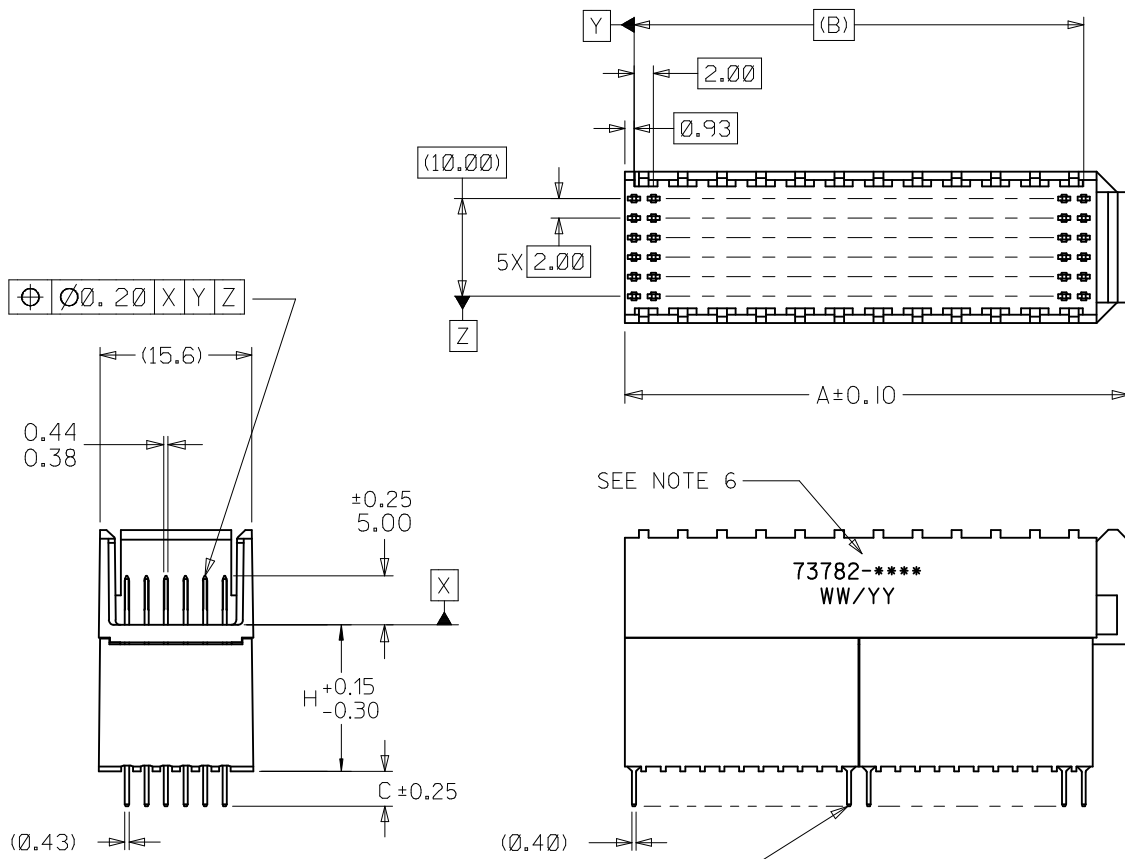
#### **Reference - Drawing Numbers**

Packaging Specification	PK-70873-0870
Product Specification	PS-73780-999
Sales Drawing	SD-73782-001

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This document was generated on 05/14/2010

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NOTES:

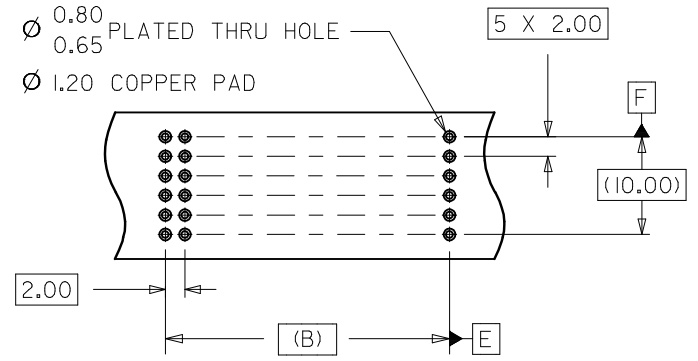
- MATERIALS: HOUSING-LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK. TERMINAL-PHOSPHOR BRONZE
- FINISH:  
0.75 MICROMETERS MINIMUM SELECTIVE GOLD IN MATING AREA  
2.50 MICROMETERS MINIMUM SELECTIVE TIN IN TAIL AREA  
NICKEL UNDERPLATE OVERALL.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
- THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS C.
- PACKAGE PER PK-70873-0870, PK-70873-0871, OR PK-70873-0875.
- PARTS MARKED WITH PART NUMBER AND DATE CODE APPROXIMATELY WHERE SHOWN.

$\varnothing 0.15$  E F

$\varnothing 0.838$  DRILL

$\varnothing 0.80$   
 $\varnothing 0.65$  PLATED THRU HOLE

$\varnothing 1.20$  COPPER PAD



BACKPLANE HOLE PATTERN

$\varnothing 0.15$  X Y Z

REVISE DIM H TOL EC NO: UCP2008-3186 DRWN:SDANNELLEY 2008/07/29 CHKD:MS:IBARRA 2008/09/11 APPR:SMILLER 2008/09/16	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	$\nabla=0$ $\sphericalangle=0$	mm INCH 4 PLACES $\pm$ --- $\pm$ --- 3 PLACES $\pm$ --- $\pm$ --- 2 PLACES $\pm 0.05$ $\pm$ --- 1 PLACE $\pm 0.10$ $\pm$ --- ANGULAR $\pm 1/2^\circ$	MM ONLY	2:1	METRIC	DRAWN BY DATE JB INGHAM 1997/04/25 CHECKED BY DATE SREED 1997/04/25 APPROVED BY DATE CB IXLER 1997/04/25	TITLE SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO.	MOLEX INCORPORATED SD-73782-001		SHEET NO. 1 OF 2
	REV		SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MATERIAL NUMBER ASSIGNMENT

73782-\* \* 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1 EC NO: UCP2008-3186 DRWN: SPANNELLY 2008/07/29 CHKD: MSIBARRA 2008/09/11 APPR: SMILLER 2008/09/16	QUALITY SYMBOLS ▽=0 ▽7=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.05 ± --- 1 PLACE ± 0.10 ± --- ANGULAR ± 1/2°	DIMENSION STYLE MM ONLY DRAWN BY DATE JB INGHAM 1997/04/25 CHECKED BY DATE SREED 1997/04/25 APPROVED BY DATE CB IXLER 1997/04/25	SCALE 1:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER	
	MATERIAL NO. SEE TABLE	MOLEX INCORPORATED	DOCUMENT NO. SD-73782-001	SHEET NO. 2 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	SIZE B					

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5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1 EC No. UDT2000-1073 DRWN: BINGHAM 00/05/08 CHK: REED 00/05/08 APPR: BIXLER 00/05/08	DESCRIPTION MAJOR $\nabla = 0$ CRITICAL $\nabla_C = 0$	GENERAL TOLERANCES: (UNLESS SPECIFIED)	SCALE NO: NE	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm INCH <input type="checkbox"/> INCH mm <input checked="" type="checkbox"/> mm ONLY	SHT REV		
		4 PLACES $\pm 0.$ $\pm.$ 3 PLACES $\pm 0.$ $\pm.$ 2 PLACES $\pm 0.N/A$ $\pm.$ 1 PLACE $\pm 0.NA/$ $\pm.$	DRAWN BY & DATE JBINGHAM 97/04/25 CHECKED BY & DATE SREED 97/04/25 APPROVED BY & DATE CBIXLER 97/04/25	TITLE: SALES ASSEMBLY HDM BACKPLANE STACKING MODULE CLOSED END OPTION SOLDER TAIL		MOLEX INCORPORATED		REVISE ON CAD ONLY
		ANGULAR: $\pm$ $^{\circ}$	CAD FILENAME S73782X2.DGN	MATERIAL NO. SEE CHART	DRAWING NO. SD-73782-001	SHEET NO. 2	SIZE B	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					